



INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁶ : H01R 9/09	A1	(11) International Publication Number: WO 00/16443 (43) International Publication Date: 23 March 2000 (23.03.00)
(21) International Application Number: PCT/US99/20418 (22) International Filing Date: 7 September 1999 (07.09.99) (30) Priority Data: 60/099,730 10 September 1998 (10.09.98) US (63) Related by Continuation (CON) or Continuation-in-Part (CIP) to Earlier Application US 60/099,730 (CIP) Filed on 10 September 1998 (10.09.98) (71) Applicant (for all designated States except US): VIASYSTEMS GROUP, INC. [US/US]; Suite 400, 101 South Hanley Road, St. Louis, MO 63105 (US). (72) Inventor; and (75) Inventor/Applicant (for US only): COTTON, Martin, A. [GB/GB]; Eldon Street, South Shields, Tyne & Wear NE33 5BU (GB). (74) Agent: EVANS, Lawrence, E., Jr.; Herzog, Crebs & McGhee, LLP, One City Centre, 24th floor, 515 North Sixth Street, St. Louis, MO 63101-2409 (US).		(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, US, UZ, VN, YU, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i>
(54) Title: NON-CIRCULAR MICRO-VIA (57) Abstract Non-circular micro-vias (102) for printed circuit boards are disclosed and a method of making them.		